

中华人民共和国中国电子行业标准 SJ/T11364-2014 (中国RoHS2)  
People's Republic of China Electronic Industry Standard SJ/T 11364-2014 (China RoHS2)



|               |                             |
|---------------|-----------------------------|
| 产品 / Product: | ZWS30B (exclude ZWS30B**/A) |
|---------------|-----------------------------|

| 零件名称 / Part Name    | 有毒有害物质或元素 / Hazardous Substances |         |         |             |             |               |
|---------------------|----------------------------------|---------|---------|-------------|-------------|---------------|
|                     | 铅<br>Pb                          | 汞<br>Hg | 镉<br>Cd | 六价铬<br>Cr6+ | 多溴联苯<br>PBB | 多溴二苯醚<br>PBDE |
| 电路模块 / PCB Assembly | X                                | ○       | ○       | ○           | ○           | ○             |

此表依照SJ/T11634-2014规定制定

This table is prepared in accordance with the provisions of SJ/T 11364-2014

|     |                                                                                                                                                                                                           |
|-----|-----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| ○ = | 指明产品所有均质材料包含的有害物质要低于GB/T26572限定的要求<br>Indicates that said hazardous substance contained in all of the homogeneous materials for this part is below the limit requirement of GB/T 26572                    |
| X = | 指明产品所用的至少一种均质材料包含的有害物质高于GB/T26572限定的要求<br>Indicates that said hazardous substance contained in at least one of the homogeneous materials used for this part is above the limit requirement of GB/T 26572. |

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| 电路模块 / PCB Assembly                  | X                                | ○       | ○       | ○           | ○           | ○             |
| 机箱 (如适用) / Enclosure (if applicable) | ○                                | ○       | ○       | ○           | ○           | ○             |

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